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- Dual Supervisory Circuits for DSP and Processor-Based Systems
- Power-On Reset Generator with Fixed Delay Time of 200 ms, no External Capacitor Needed
- Watchdog Timer Retriggers the RESET Output at SENSEn ≥ V_{IT+}
- Temperature-Compensated Voltage Reference
- Maximum Supply Current of 40 μA
- Supply Voltage Range . . . 2.7 V to 6 V
- Defined RESET Output from $V_{DD} \ge 1.1 V$
- MSOP-8 and SO-8 Packages
- Temperature Range . . . 40°C to 85°C

typical applications

Figure 1 lists some of the typical applications for the TPS3305 family, and a schematic diagram for a DSP-based system application. This application uses TI part numbers TPS3305–25, TPS7133, TPS71025, and TMS320VC549.

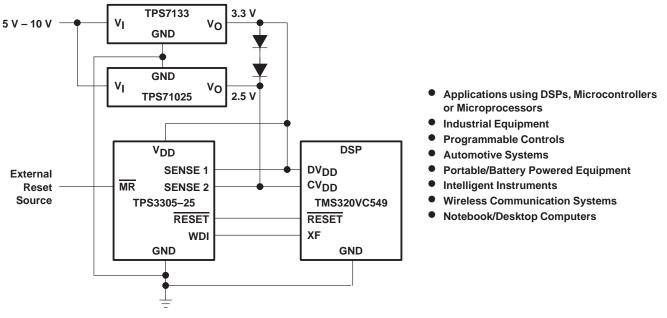


Figure 1. Applications Using the TPS3305 Family

description

The TPS3305 family is a series of micropower supply voltage supervisors designed for circuit initialization, primarily in DSP and processor-based systems, which require two supply voltages.

The product spectrum of the TPS3305 is designed for monitoring two independent supply voltages of 3.3 V/1.8 V, 3.3 V/2.5 V or 3.3 V/5 V.

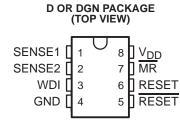


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description (continued)

The various supply voltage supervisors are designed to monitor the nominal supply voltage, as shown in the following supply voltage monitoring table.

DEVICE	NOMINAL SUPE	RVISED VOLTAGE	THRESHOLD	VOLTAGE (TYP)
DEVICE	SENSE1	SENSE2	SENSE1	SENSE2
TPS3305-18	3.3 V	1.8 V	2.93 V	1.68 V
TPS3305-25	3.3 V	2.5 V	2.93 V	2.25 V
TPS3305-33	5 V	3.3 V	4.55 V	2.93 V

SUPPLY VOLTAGE MONITORING

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors the SENSEn inputs and keeps $\overline{\text{RESET}}$ active as long as SENSEn remains below the threshold voltage V_{IT+}.

An internal timer delays the return of the $\overline{\text{RESET}}$ output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d typ} = 200 \text{ ms}$, starts after SENSE1 and SENSE2 inputs have risen above the threshold voltage V_{IT+} . When the voltage at SENSE1 or SENSE2 input drops below the threshold voltage V_{IT-} , the RESET output becomes active (low) again.

The TPS3305-xx devices integrate a watchdog timer that is periodically triggered by a positive or negative transition of WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, $t_{t(out)} = 1.6$ s, RESET becomes active for the time period t_d . This event also reinitializes the watchdog timer. Leaving WDI unconnected disables the watchdog.

The TPS3305-xx family of devices incorporates a manual reset input, MR. A low level at MR causes RESET to become active. In addition to the active-low RESET output, the TPS3305-xx family includes an active-high RESET output.

The TPS3305-xx devices are available in either 8-pin MSOP or standard 8-pin SO packages.

The TPS3305-xx family is characterized for operation over a temperature range of – 40°C to 85°C.

	PACKAGE	D DEVICES							
TA	SMALL OUTLINE (D)	PowerPAD™ μ-SMALL OUTLINE (DGN)	MARKING DGN PACKAGE	CHIP FORM (Y)					
	TPS3305-18D	TPS3305-18DGN	TIAAM	TPS3305-18Y					
–40°C to 85°C	TPS3305-25D	TPS3305-25DGN	TIAAN	TPS3305-25Y					
	TPS3305-33D	TPS3305-33DGN	TIAAO	TPS3305-33Y					

AVAILABLE OPTIONS

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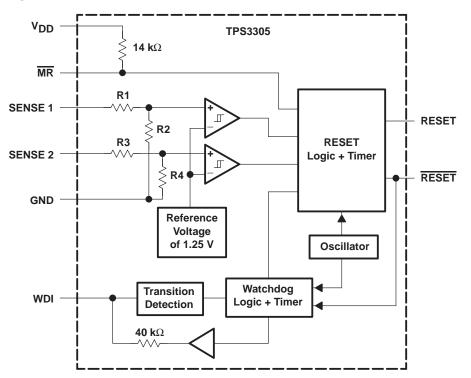
description (continued)

FUNCTION/IRUTH TABLES							
MR	SENSE1>VIT1	E1>VIT1 SENSE2>VIT2		RESET			
L	X‡	X‡	L	Н			
Н	0	0	L	н			
Н	0	0	L	н			
н	0	1	L	Н			
н	0	1	L	Н			
н	1	0	L	Н			
н	1	0	L	н			
Н	1	1	L	н			
н	1	1	Н	L			

FUNCTION/TRUTH TABLES

† X = Don't care

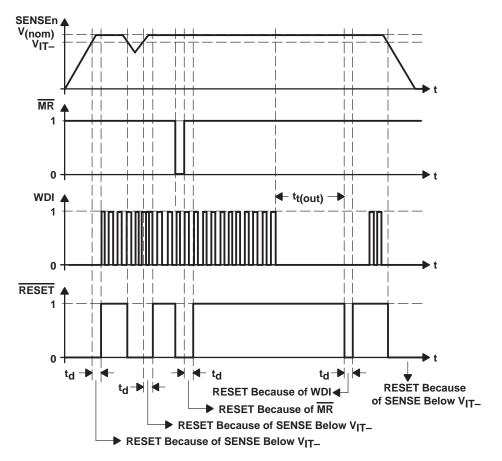
functional block diagram





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timing diagram

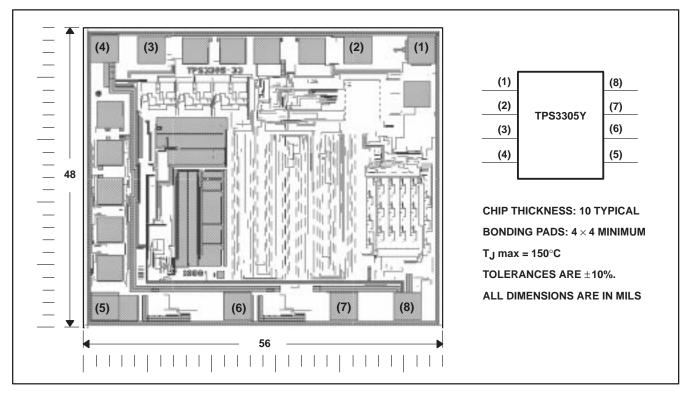




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TPS3305Y chip information

These chips, when properly assembled, display characteristics similar to those of the TPS3305. Thermal compression or ultrasonic bonding may take place on the doped aluminium bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.



Terminal Functions

TERMIN	TERMINAL I/O		DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
GND	4		Ground
MR	7	Ι	Manual reset
RESET	5	0	Active-low reset output
RESET	6	0	Active-high reset output
SENSE1	1	Ι	Sense voltage input 1
SENSE2	2	Ι	Sense voltage input 2
WDI	3	I	Watchdog timer input
V _{DD}	8		Supply voltage



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{DD} (see Note1) All other pins (see Note 1)	
Maximum low output current, I _{OL}	
Maximum high output current, I _{OH}	
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stg}	–65°C to 150°C
Soldering temperature	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than t = 1000 h continuously.

DISSIPATION RATING TABLE							
PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING			
DGN	2.14 mW	17.1 mW/°C	1.37 mW	1.11 mW			
D	725 mW	5.8 mW/°C	464 mW	377 mW			

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2.7	6	V
Input voltage at MR and WDI, VI	0	V _{DD} +0.3	V
Input voltage at SENSE1 and SENSE2, VI	0	(V _{DD} +0.3)V _{IT} /1.25V	V
High-level input voltage at \overline{MR} and WDI, VIH	0.7xV _{DD}		V
Low-level input voltage at \overline{MR} and WDI, VIL		0.3×V _{DD}	V
Input transition rise and fall rate at $\overline{\text{MR}}$, $\Delta t / \Delta V$		50	ns/V
Operating free-air temperature range, TA	-40	85	°C



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	PARAMETER		TEST CON	DITIONS	MIN	TYP	MAX	UNIT	
			V _{DD} = 2.7 V to 6 V	/, I _{OH} = –20 μA	V _{DD} - 0.2V				
Vон	High-level output voltage		V _{DD} = 3.3 V,	I _{OH} = -2 mA	V _{DD} - 0.4V			V	
			V _{DD} = 6 V,	I _{OH} = –3 mA	V _{DD} - 0.4V				
	Low-level output voltage		V _{DD} = 2.7 V to 6 \	/, I _{OL} = 20 μA			0.2		
Vol			V _{DD} = 3.3 V,	I _{OL} = 2 mA			0.4	V	
		V _{DD} = 6 V,	IOL = 3 mA			0.4			
	Power-up reset voltage (see Note 2)		$V_{DD} \ge 1.1 V$,	I _{OL} = 20 μA			0.4	V	
					1.64	1.68	1.72		
		VSENSE1,	$V_{DD} = 2.7 V \text{ to } 6 V$	ν,	2.20	2.25	2.30	v	
		VSENSE2	$T_A = 0^{\circ}C$ to $85^{\circ}C$		2.86	2.93	3	V	
V _{IT}	Negative-going input threshold voltage (see Note 3)				4.46	4.55	4.64		
					1.64	1.68	1.73		
		VSENSE1,	$V_{DD} = 2.7 V \text{ to } 6 V_{DD}$	Ι,	2.20	2.25	2.32		
		VSENSE2	$T_{A} = -40^{\circ}C$ to 85°C		2.86	2.93	3.02	02 V	
					4.46	4.55	4.67		
	Hysteresis at VSENSEn input		V _{IT} = 1.68 V			15			
N/			V _{IT} _ = 2.25 V			20		m\/	
V _{hys}			V _{IT} _ = 2.93 V			30		_ m∨	
		V _{IT} = 4.55 V			40				
h iza o	Average high-level input current		$WDI = V_{DD} = 6 V$			100	150		
IH(AV)	Average high-level liput current	WDI	Time average (dc	= 88%)		100	150	μA	
IL(AV)	Average low-level input current		WDI = 0 V,	$V_{DD} = 6 V,$		-15	-20	μΛ	
'L(AV)			Time average (dc			10	20		
		WDI	$WDI = V_{DD} = 6 V,$			120	170		
Н	High-level input current	MR	$\overline{\text{MR}} = 0.7 \times \text{V}_{\text{DD}},$			-130	-180	μA	
Η		SENSE1	$VSENSE1 = V_{DD}$			5	8	μΑ	
		SENSE2	$VSENSE2 = V_{DD}$	= 6 V		6	9		
		WDI	WDI = 0 V,	V _{DD,} = 6 V		-120	-170		
۱L	Low-level input current	MR	$\overline{MR} = 0V,$	$V_{DD} = 6 V$		-430	-600	μA	
		SENSEn	VSENSE1,2 = 0 V		-1		1		
IDD	Supply current						40	μΑ	
Ci	Input capacitance		$V_{I} = 0 V \text{ to } V_{DD}$			10		pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

NOTES: 2. The lowest supply voltage at which RESET becomes active. t_r , $V_{DD} \ge 15 \,\mu$ s/V.

3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic 0.1 µF) should be placed close to the supply terminals.



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timing requirements at V_DD = 2.7 V to 6 V, R_L = 1 M\Omega, C_L = 50 pF, T_A = 25 ^{\circ}C

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
	SENSEn	$V_{SENSEnL} = V_{IT-} - 0.2 V,$	VSENSEnH = VIT+ +0.2 V	6			μs	
tw	t _w Pulse width	MR			100			ns
		WDI	$V_{IH} = 0.7 \times V_{DD},$	$V_{IL} = 0.3 \times V_{DD}$	100			ns

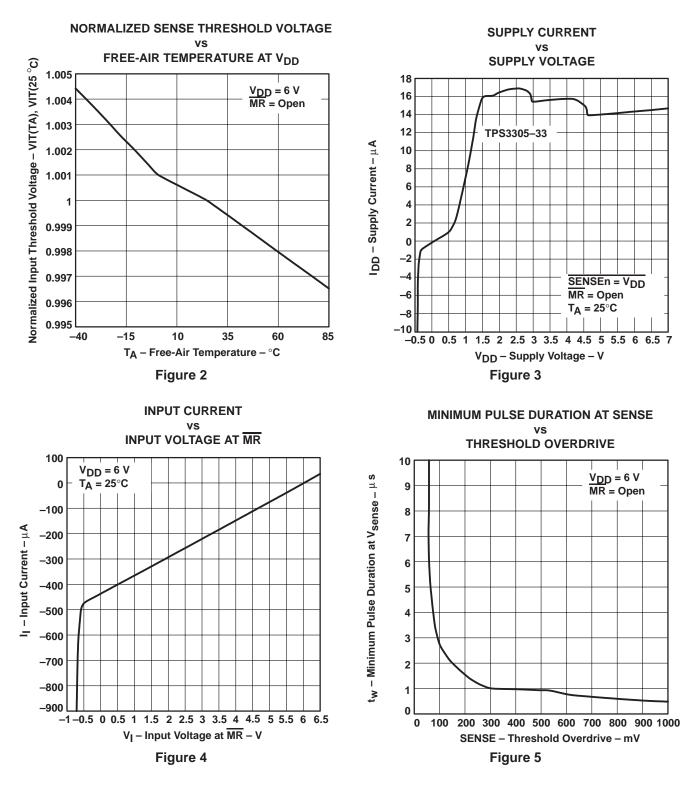
switching characteristics at V_DD = 2.7 V to 6 V, R_L = 1 M\Omega, C_L = 50 pF, T_A = 25^{\circ}C

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t t(out)			$\frac{V_{I(SENSEn)} \ge V_{IT+} + 0.2 \text{ V,}}{MR} \ge 0.7 \times V_{DD}, \text{ See timing diagram}$	1.1	1.6	2.3	S
t _d	Delay time		$\frac{V_{I(SENSEn)} \ge V_{IT+} + 0.2 \text{ V,}}{MR} \ge 0.7 \times V_{DD}, \text{ See timing diagram}$	140	200	280	ms
^t PHL	Propagation (delay) time, high-to-low level output	MR to RESET, MR to RESET	to RESET $V_{1}(SENSER) > V_{1T_1} + 0.2 V_{1}$	200	500	20	
^t PLH	Propagation (delay) time, low-to-high level output	MR to RESET, MR to RESET	$V_{IH} = 0.7 \times V_{DD}, V_{IL} = 0.3 \times V_{DD}$		200	500	ns
tPHL	Propagation (delay) time, high-to-low level output	SENSEn to RESET, SENSEn to RESET	V _{IH} = V _{IT+} +0.2 V, V _{IL} = V _{IT-} -0.2 V,		1	5	
^t PLH	Propagation (delay) time, low-to-high level output	SENSEn to RESET, SENSEn to RESET	$\overline{\text{MR}} \ge 0.7 \times \text{V}_{DD}$		1	5	μs



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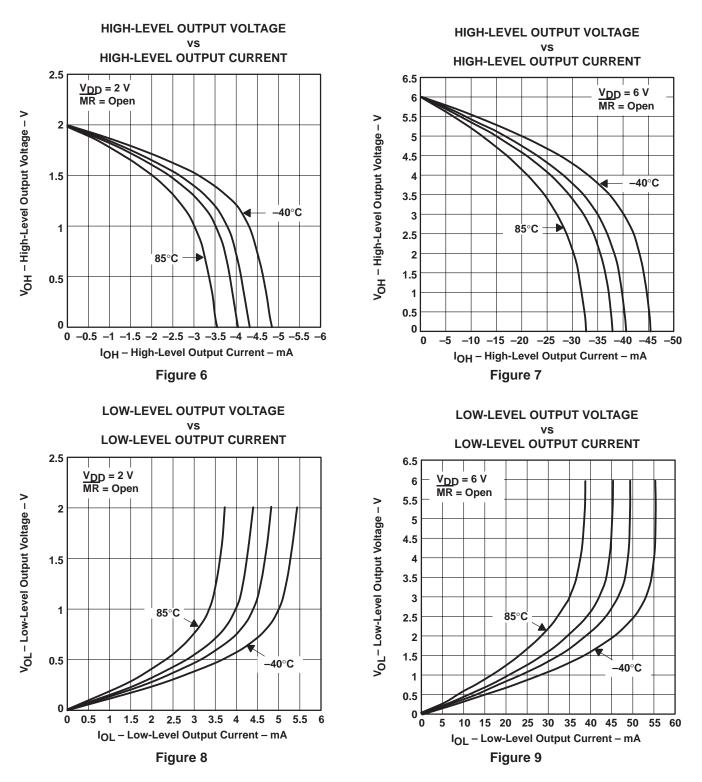






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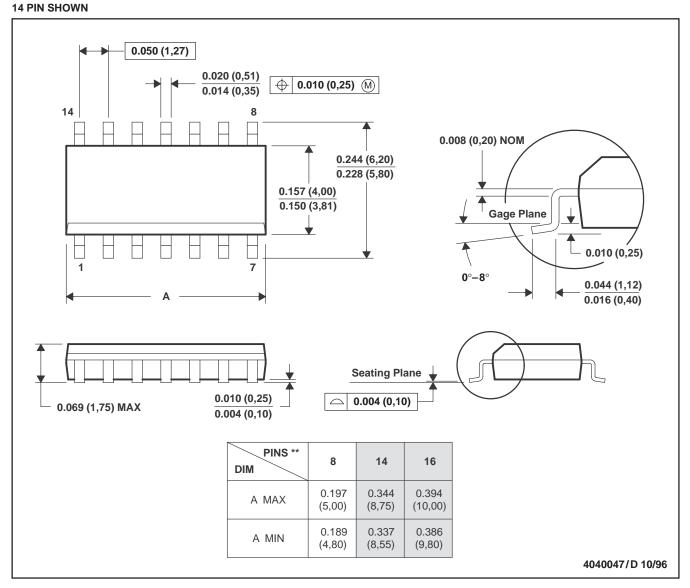


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MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

D (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

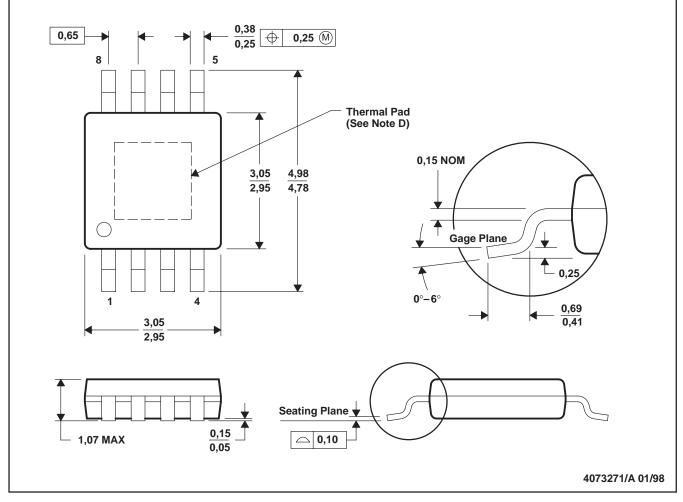


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MECHANICAL DATA

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions include mold flash or protrusions.

D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

E. Falls within JEDEC MO-187

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